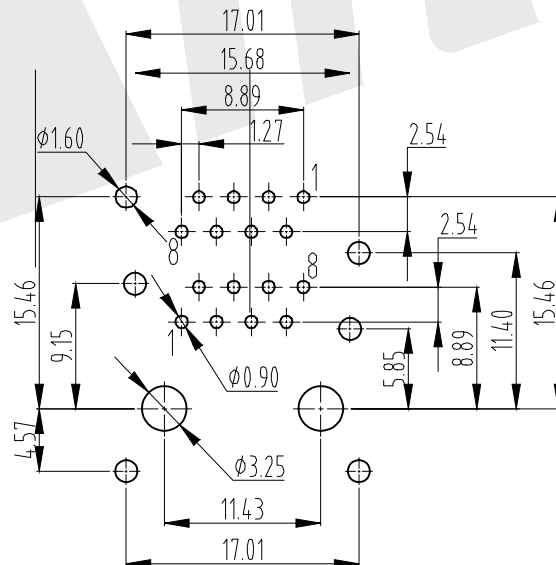
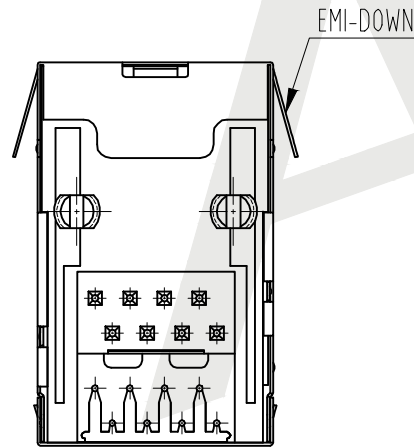
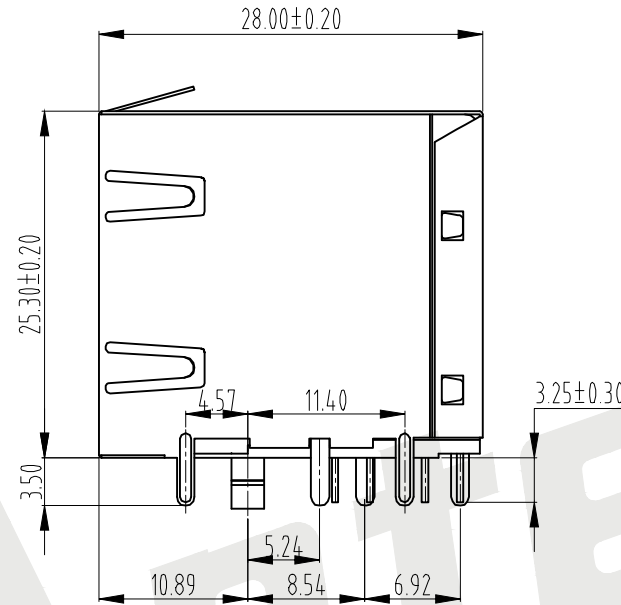
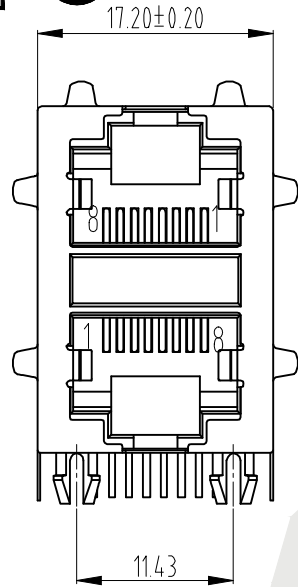


HSF

RoHS



PCB LAYOUT/TOP VIEW

NOTES:
MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
 2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
 3. PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
 4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE
- ELECTRICAL
1. VOLTAGE RATING: 125V AC RMS
 2. CURRENT RATING: 1.5AMP
 3. CONTACT RESISTANCE: 30 MILLIOHMS MAX
 4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
 5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTION PRB-SOLDER: 1 LB MIN

REVRONMENTAL

1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5921 - 8P - 8C - X - C2 - G

① ② ③ ④ ⑤ ⑥

- | | |
|---|-------------------|
| ① SERIES NO: | ⑤ Shield |
| ② NUMBER OF POSITIONS (10P, 8P, 6P, 4P) | A: W/O Shield |
| ③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C) | B: Half Shield |
| ④ Contact Plating | C: Shield W/Eml |
| G0: Gold flash | D: Shield W/O Eml |
| G1: 3U" Gold | ⑥ Ports |
| G2: 5U" Gold | A: 1X1P G: 2*1P |
| G3: 10U" Gold | B: 1X2P H: 2*2P |
| G4: 15U" Gold | C: 1X4P I: 2*3P |
| G5: 30U" Gold | D: 1X5P J: 2*4P |
| SN: Tin | E: 1X6P K: 2*6P |
| | F: 1X8P L: 2*8P |

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

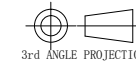
Antenk® ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 22/03/2018
CHECK BobYang DATE 22/03/2018

TITLE: RJ45 Jack side entry full shielded 2X1P with EMI

DRAWING NO: ATRJ5921-8P8C-X-C2-G

PRODUCT NO: ATRJ5921-8P8C-X-C2-G



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		